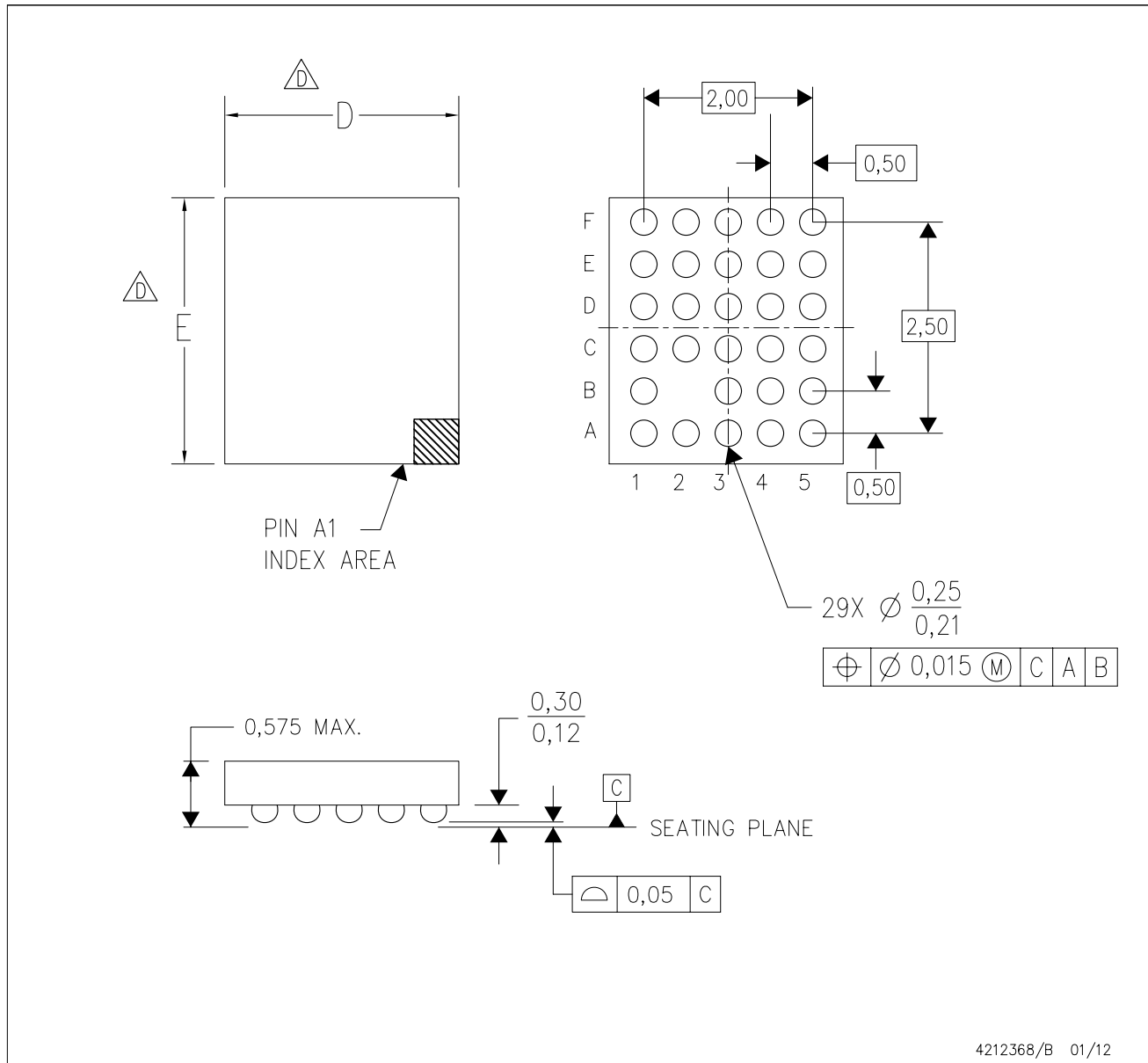


YPB (R-XBGA-N29)

DIE-SIZE BALL GRID ARRAY (WCSP)



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - The package size (Dimension D and E) of a particular device is specified in the device Product Data Sheet version of this drawing, in case it cannot be found in the product data sheet please contact a local TI representative.
  - Reference Product Data Sheet for array population.  
5 x 6 depopulated matrix pattern is shown for illustration only.
  - F. This package is a Pb-free solder ball design.

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